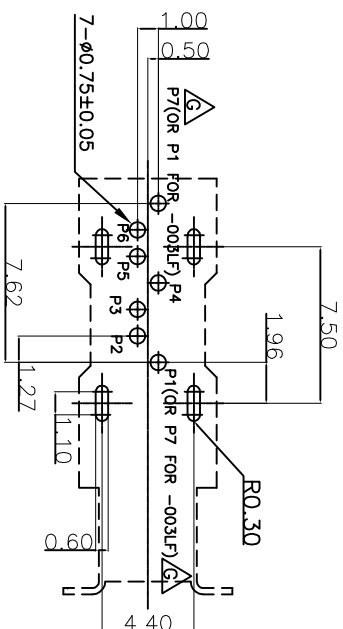
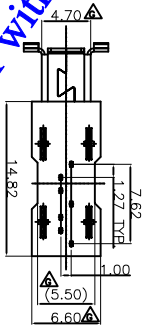
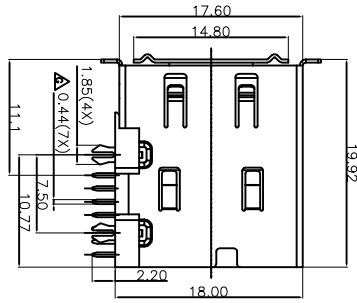
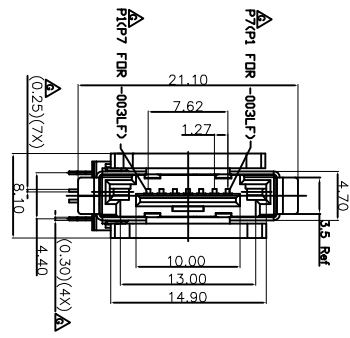
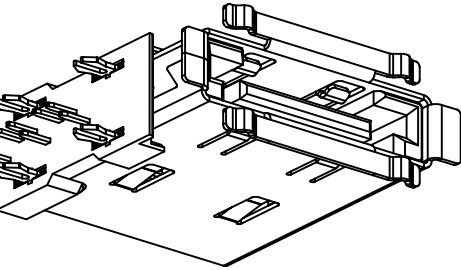


PRODUCT NO.
10074141-001LF
10074141-003LF



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RECOMMEND P.C.B.O.A.R.D. LAYOUT
PCB TOLERANCE:±0.05

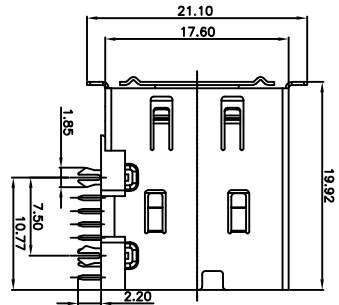
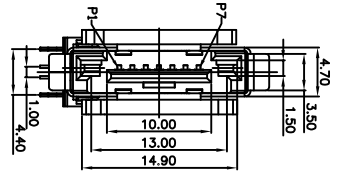
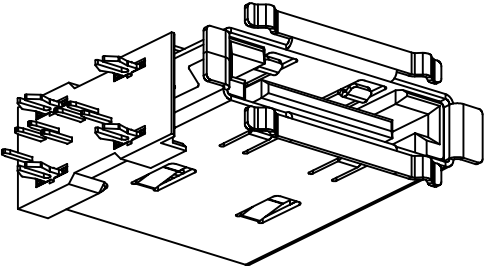


PIN DEFINITION

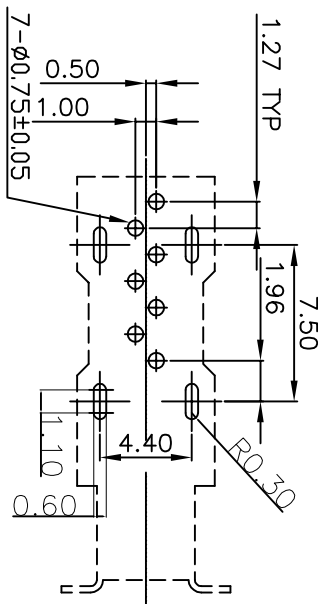
ESATA	NAME	TYPE
P1	GND	GND
P2	A+	A+
P3	A-	A-
P4	GND	GND
P5	B-	B-
P6	B+	B+
P7	GND	GND

mat'l. code	14	surface	ISO 1302	tolerance	ISO 406	ISO 100	projection	product family	533
ltr	ecn no	dr	date	ISO 1302	tolerance unless otherwise specified	ISO 100	projection	product family	533
A	107-1074S	LIN	2007-05-23	angles	.XX±0.25	MM		E-SATA_UP_RIGHT	
B	108-1082S	LIN	2008-04-28	linear	.XX±0.25	MM		DIP_TYPE	
C	110-0184S	LIN	2010-12-14	linear	.XXX±0.100	scale 2:1			
D	T-00544QS	LIN	2011-08-31	STERLING	LIN	2007-05-21			
E	EX-S-00781	HKL	2011-10-17	ENG	HKLIM	2016-03-03			
F	EX-S-01181	HKL	2012-06-08	CH	HKLIM	2016-03-03			
G	EX-S-23401	HKL	2016-03-03	DPD	KPTAY	2016-03-03			
Sheet	Revision	G	G	G	107109	111113	115117	119121	123125
Index	Sheet	1	2	3	106108	110112	114116	118120	122124
					126128	130132	134136	138139	

- NOTES:
1. MATERIAL: HOUSING: THERMAL PLASTIC HIGH TEMP WITH 30% G/F US94 V-0
 2. FINISH: 50U" MIN. NICKEL UNDERPLATING OVER ALL CONTACTS, COPPER ALLOY SHELL/BOARD LOOKS OVER COPPER ALLOY
 3. THE HOUSING WILL WITHSTAND TO 280C FOR 10 SEC IN A WAVE SOLDER APPLICATION WITH A 1.6MM PCB
 4. PRODUCT SPEC : GS-12-386
 5. PACKING SPEC : GS-14-1109
 6. A SYMBOL Δ WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION
- PACKING: TRAY PACKING
BLANK: TRAY PACKING
1. 15U" GOLD PLATING
2. 2U" G/F GOLD PLATING
3. 15U" GOLD PLATING WITH NEW PINOUT ASSIGNMENT
- 0: LAYOUT?!



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P.C. BOARD MOUNTING DIMENSIONS T=1.60mm
PCB TOLERANCE: ±0.05

PIN DEFINITION

ESATA	NAME	TYPE
P1	GND	A+
P2	A+	A-
P3	A-	GND
P4	GND	B-
P5	B-	B+
P6	B+	GND
P7	GND	

mat'l. code	14	surface	sg	tolerance	projection	product family															
lfr	ecm no	dr	date	ISO 1302	ISO 406	ISO 100															
A	107-1074S	LIN	2007-05-23	tolerances unless otherwise specified	MM	533															
B	108-1082S	LIN	2008-04-28	angle	.XX±0.38	E-SATA_UP_RIGHT															
C	110-0184S	LIN	2010-12-14	linear	.XX±0.25	DIP_TYPE															
D	T-00544QS	LIN	2011-08-31	σ±Z	.XXX±0.100	scale 2:1															
E	ex-s-00781	HKL	2011-10-17	STERLING	LIN	2007-05-21															
F	ex-s-01187	HKL	2012-06-08	HKLIM	2016-03-03																
G	ex-s-2340	HKL	2016-03-03	KPTAY	2016-03-03																
Sheet	revision	G	G	107	109	111	113	115	117	119	121	123	125	127	129	131	133	135	137	139	
index	sheet	1	2	3	106	108	110	112	114	116	118	120	122	124	126	128	130	132	134	136	138

- NOTES:
1. MATERIAL: HOUSING: THERMAL PLASTIC HIGH TEMP WITH 30% G/F U194 V-0 COLOR: BLACK CONTACT: COPPER ALLOY SHELL/BOARD LOCK: COPPER ALLOY
 2. CONTACT: GOLD PLATING ON CONTACT AREA 100µ" MIN. WATT TIN PLATING ON SOLDERMILLS 50µ" MIN. NICKEL UNDERPLATING OVER ALL BOARD LOCK: 50µ" MIN. NICKEL PLATING OVER ALL SHELL/BOARD LOCK: 50µ" MIN. NICKEL PLATING OVER ALL
 3. IN A WAVE SOLDER APPLICATION WITH A 1.5MM PCB
 4. PRODUCT SPEC : GS-12-398
 5. PACKING SPEC : GS-14-1109
 6. PRODUCT NUMBERING: 10074141 - 0 0 0 LF LEAD FREE
- PAKING: BLANK: TRAY PACKING
1: 15µ" GOLD PLATING
2: 6/7 GOLD PLATING
6. A SYMBOL Δ WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE, WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION
- 1: LAYOUT/2



dwg no 10074141 sheet 2 of 3 size A3

1

2

3

4

5

6

1

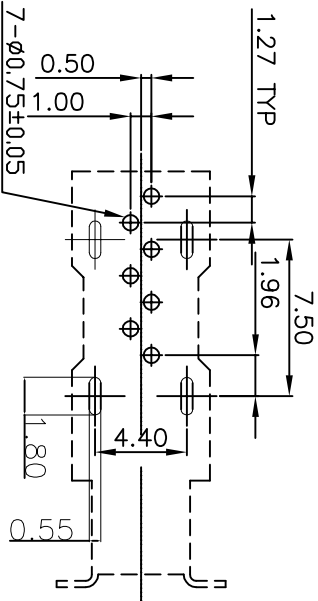
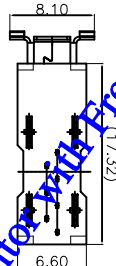
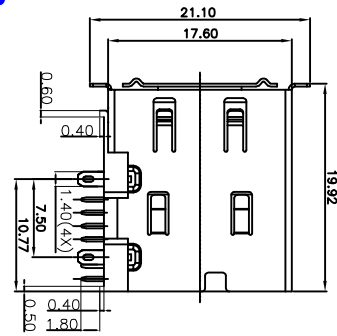
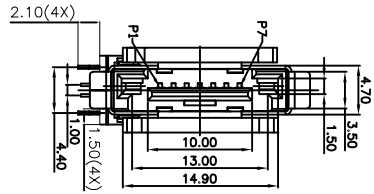
2

3

4

5

6



P.C.B. BOARD MOUNTING DIMENSIONS T=1.60mm
PCB TOLERANCE: ±0.05

PIN DEFINITION	
ESATA	NAME TYPE
	P1 GND
	P2 A+
	P3 A-
	P4 GND
	P5 B-
	P6 B+
	P7 GND

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mat'l. code	14	surface	ISO 1302	ISO 406	ISO 150	100	projection	product family	533												
lfr	ecn no	dr	date	tolerances unless otherwise specified	angles	linear	XXX±0.100	MM													
A	107-1074S	UN	2007-05-23																		
B	108-1082S	UN	2008-04-28																		
C	110-0184S	UN	2010-12-14	0±Z																	
D	1-00544QS	UN	2011-08-31	dr																	
E	6x-8-0078H	HKL	2011-10-17	engr																	
F	6x-8-0118H	HKL	2012-06-08	chr																	
G	6x-8-234H	HKL	2016-03-03	dpd																	
Sheet	Revision	1	2	3	107109	111	113	115	117	119	121	123	125	127	129	131	133	135	137	139	
Index	Sheet	G	G	G	106	108	110	112	114	116	118	120	122	124	126	128	130	132	134	136	138

- NOTES:
1. MATERIAL: THERMOPLASTIC HIGH TEMP WITH 30% G/F UL94 V-0 ROUSING: COLOR:BLACK
 2. FINISH: CONTACT: COPPER ALLOY SHELL/BOARD LOCK: COPPER ALLOY
 3. CONTRACT: GOLD PLATING ON CONTACT AREA
 4. BOARD LOCK: 50μ" MIN. NICKEL UNDERPLATING OVER ALL SHELL/BOARD LOCK: 50μ" MIN. NICKEL PLATING OVER ALL IN A WAVE SOLDER APPLICATION WITH A 1.5MM PCB
 5. PRODUCT SPEC: 05-12-386
 6. PACKING SPEC: 05-14-1109
 7. PRODUCT NUMBERING: 10074141 - 2 0 X X X LF - LEAD FREE
- 2: LAYOUTS
- 1: 15μ" GOLD PLATING
- 2: 0.7μ" GOLD PLATING
- PACKING: TRAY PACKING
- BLANK: TRAY PACKING
6. A SYMBOL Δ WILL BE NEXT TO ANY DIMENSION, VIEW OR NOTE, WHICH HAS BEEN MODIFIED WITH THE CURRENT DRAWING REVISION